

AMENDMENTS TO THE CLAIMS:

The following listing of claims replaces all prior listings, and all prior versions, of claims in the application.

LISTING OF CLAIMS:

1. (Previously presented) An adhesive film for bonding circuit members, said adhesive film adapted to be put between circuit electrodes facing each other, with said circuit electrodes facing each other being pressed interposing the adhesive film between them, to interconnect the electrodes electrically in the direction of pressing,

wherein said adhesive film comprises:

a first adhesive layer which includes an adhesive resin composition and an insulative inorganic filler;

said insulative inorganic filler being contained in an amount of from 10 to 200 parts by weight based on 100 parts by weight of the adhesive resin composition;

said adhesive film having an average coefficient of thermal expansion of 200 ppm/°C or below at 110 to 130°C after curing; and

the adhesive film further comprising conductive particles in an amount of from 0.1 to 30 parts by volume based on 100 parts by volume of the adhesive resin composition.

2. (Previously presented) An adhesive film for bonding circuit members according to claim 1, said adhesive film further comprising a second adhesive layer containing an adhesive resin composition as a main ingredient.

3. (Previously presented) An adhesive film for bonding circuit members according to claim 1, said adhesive film further comprising a second adhesive layer containing an adhesive resin composition as a main ingredient and having a modulus of elasticity of from 100 to 2,000 MPa at 40°C after curing.

4. (Cancelled).

5. (Previously presented) The adhesive film for bonding circuit members according to claim 1, which has an average coefficient of thermal expansion of from 30 to 200 ppm/°C at 110 to 130°C after curing of the adhesive film.

6. (Previously presented) An adhesive film for bonding circuit members, said adhesive film adapted to be put between circuit electrodes facing each other; said circuit electrodes facing each other being pressed interposing the adhesive between them, to interconnect the electrodes electrically in the direction of pressing,

wherein said adhesive film comprises:

a multi-layer constitution having a third adhesive layer and a fourth adhesive layer which have physical properties different in value from each other,

wherein said third adhesive layer has a coefficient of thermal expansion at 30° to 100°C, of from 20 to 70 ppm/°C, and

wherein at least one layer of said third and fourth adhesive layers contains an adhesive resin composition and an insulative inorganic filler in an amount of from 10 to 200 parts by weight based on 100 parts by weight of the adhesive resin composition.

7. (Previously presented) The adhesive film for bonding circuit members according to claim 6, wherein said third adhesive layer has a modulus of elasticity after curing which is higher than the modulus of elasticity after curing of said fourth adhesive layer.

8. (Previously presented) The adhesive film for bonding circuit members according to claim 7, wherein said fourth adhesive layer has a modulus of elasticity of from 100 to 2,000 MPa at 40°C after curing.

9. (Previously presented) The adhesive film for bonding circuit members according to claim 6, wherein said third adhesive layer has a coefficient of thermal expansion which is smaller than the coefficient of thermal expansion of the fourth adhesive layer.

10. (Cancelled).

11. (Previously presented) The adhesive film for bonding circuit members according to claim 6, wherein said third adhesive layer has a glass transition temperature which is higher than the glass transition temperature of the fourth adhesive layer.

12. (Previously presented) The adhesive film for bonding circuit members according to claim 11, wherein said third adhesive layer has a glass transition temperature of 120°C or above.

13. (Cancelled).

14. (Previously presented) The adhesive film for bonding circuit members according to claim 1, wherein said insulative inorganic filler has an average particle diameter of 3 μm or smaller.

15. (Cancelled).

16. (Previously presented) The adhesive film for bonding circuit members according to claim 1, wherein the conductive particles have a larger average particle diameter than the average particle diameter of said insulative inorganic filler.

17. (Previously presented) The adhesive film for bonding circuit members according to claim 1, which has a modulus of elasticity of from 30 to 2,000 MPa at 40°C after the curing of the adhesive resin composition.

18. (Previously presented) The adhesive film for bonding circuit members according to claim 1, wherein said adhesive resin composition contains an epoxy resin and a latent curing agent.

19. (Previously presented) The adhesive film for bonding circuit members according to claim 1, wherein said adhesive resin composition contains an epoxy resin, an acrylic rubber and a latent curing agent.

20. (Previously presented) The adhesive film for bonding circuit members according to claim 19, wherein said acrylic rubber contains a glycidyl ether group in the molecule.

21. – 31. (Cancelled).

32. (Previously presented) An adhesive film for bonding circuit members according to claim 1, consisting of said first adhesive layer.

33. and 34. (Cancelled).